

TC74AC273P, TC74AC273F, TC74AC273FW, TC74AC273FT

OCTAL D - TYPE FLIP FLOP WITH CLEAR

The TC74AC273 is an advanced high speed CMOS OCTAL D - TYPE FLIP FLOP fabricated with silicon gate and double - layer metal wiring C²MOS technology.

It achieves the high speed operation similar to equivalent Bipolar Schottky TTL while maintaining the CMOS low power dissipation.

Information signals applied to D inputs are transferred to the Q output on the positive going edge of the clock pulse.

When the $\overline{\text{CLR}}$ input is held “L”, the Q outputs are at a low logic level independent of the other inputs.

All inputs are equipped with protection circuits against static discharge or transient excess voltage.

FEATURES :

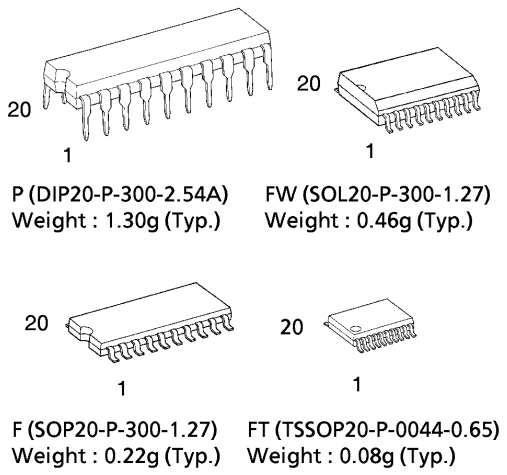
- High Speed..... $f_{\text{MAX}} = 170\text{MHz}(\text{typ.})$
at $V_{\text{CC}} = 5\text{V}$
- Low Power Dissipation..... $I_{\text{CC}} = 8\mu\text{A}(\text{Max.})$ at $T_{\text{a}} = 25^{\circ}\text{C}$
- High Noise Immunity..... $V_{\text{NIH}} = V_{\text{NIL}} = 28\% V_{\text{CC}} (\text{Min.})$
- Symmetrical Output Impedance... $|I_{\text{OH}}| = |I_{\text{OL}}| = 24\text{mA}(\text{Min.})$
Capability of driving 50Ω transmission lines.
- Balanced Propagation Delays..... $t_{\text{PLH}} \approx t_{\text{PHL}}$
- Wide Operating Voltage Range.... $V_{\text{CC}} (\text{opr}) = 2\text{V} \sim 5.5\text{V}$
- Pin and Function Compatible with 74F273

TRUTH TABLE

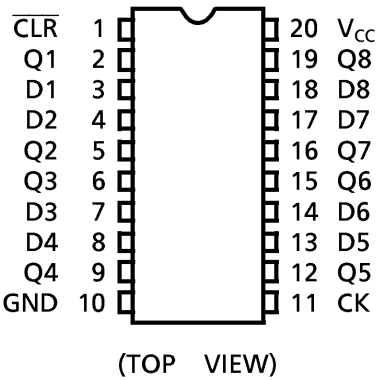
INPUTS			OUTPUTS	FUNCTION
$\overline{\text{CLR}}$	D	CK	Q	
L	X	X	L	CLEAR
H	L		L	—
H	H		H	—
H	X		Q_n	NO CHANGE

X : Don't Care

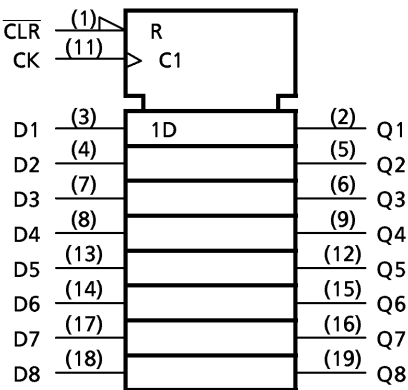
(Note) The JEDEC SOP (FW) is not available in Japan.



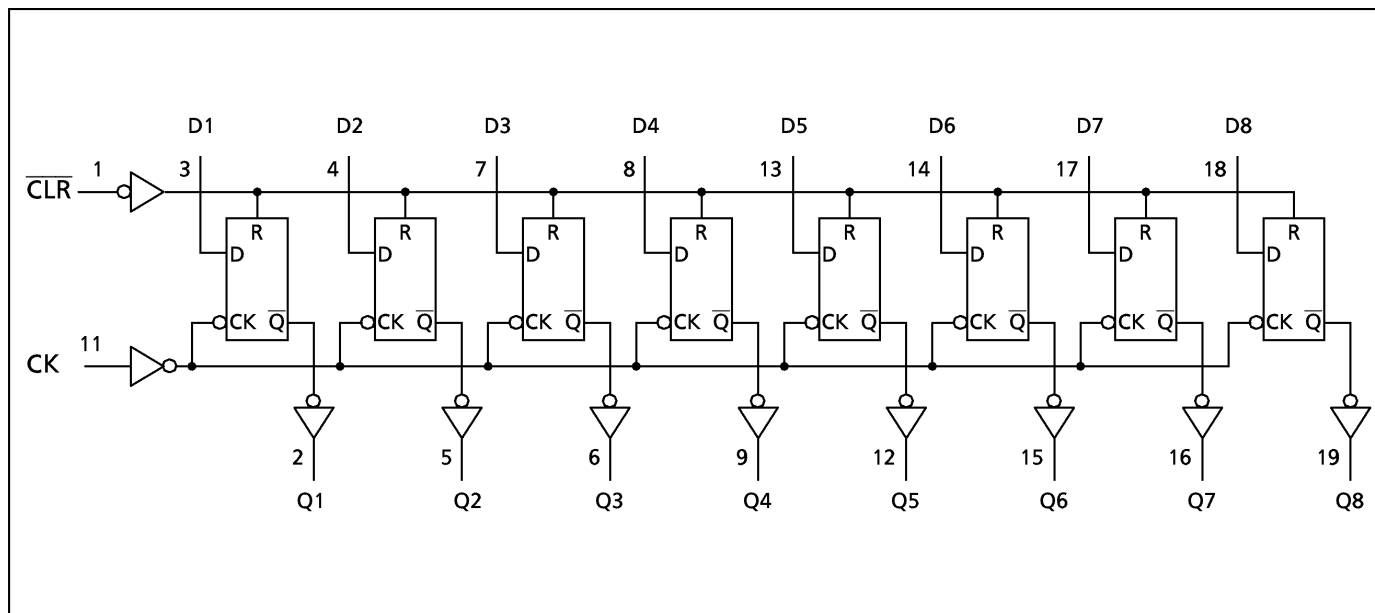
PIN ASSIGNMENT



IEC LOGIC SYMBOL



SYSTEM DIAGRAM



ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	VALUE	UNIT
Supply Voltage Range	V_{CC}	$-0.5 \sim 7.0$	V
DC Input Voltage	V_{IN}	$-0.5 \sim V_{CC} + 0.5$	V
DC Output Voltage	V_{OUT}	$-0.5 \sim V_{CC} + 0.5$	V
Input Diode Current	I_{IK}	± 20	mA
Output Diode Current	I_{OK}	± 50	mA
DC Output Current	I_{OUT}	± 50	mA
DC V_{CC} /Ground Current	I_{CC}	± 200	mA
Power Dissipation	P_D	500 (DIP)* / 180 (SOP/TSSOP)	mW
Storage Temperature	T_{stg}	$-65 \sim 150$	$^{\circ}\text{C}$

*500mW in the range of $T_a = -40^{\circ}\text{C} \sim 65^{\circ}\text{C}$. From $T_a = 65^{\circ}\text{C}$ to 85°C a derating factor of $-10\text{mW}/^{\circ}\text{C}$ should be applied up to 300mW.

RECOMMENDED OPERATING CONDITIONS

PARAMETER	SYMBOL	VALUE	UNIT
Supply Voltage	V _{CC}	2.0~5.5	V
Input Voltage	V _I N	0~V _{CC}	V
Output Voltage	V _O UT	0~V _{CC}	V
Operating Temperature	T _{opr}	− 40~85	°C
Input Rise and Fall Time	dt / dV	0~ 100 (V _{cc} = 3.3 ± 0.3V) 0~ 20 (V _{cc} = 5 ± 0.5V)	ns / V

DC ELECTRICAL CHARACTERISTICS

PARAMETER	SYMBOL	TEST CONDITION	V _{CC} (V)	Ta = 25°C			Ta = -40~85°C		UNIT
				MIN.	TYP.	MAX.	MIN.	MAX.	
High - Level Input Voltage	V _{IH}		2.0 3.0 5.5	1.50 2.10 3.85	— — —	— — —	1.50 2.10 3.85	— — —	V
Low - Level Input Voltage	V _{IL}		2.0 3.0 5.5	— — —	— — —	0.50 0.90 1.65	— — —	0.50 0.90 1.65	V
High - Level Output Voltage	V _{OH}	V _{IN} = V _{IH} or V _{IL}	I _{OH} = -50μA	2.0 3.0 4.5	1.9 2.9 4.4	2.0 3.0 4.5	— — —	1.9 2.9 4.4	V
			I _{OH} = -4mA	3.0	2.58	—	—	2.48	
			I _{OH} = -24mA	4.5	3.94	—	—	3.80	
			I _{OH} = -75mA*	5.5	—	—	—	3.85	
Low - Level Output Voltage	V _{OL}	V _{IN} = V _{IH} or V _{IL}	I _{OL} = 50μA	2.0 3.0 4.5	— — —	0.0 0.0 0.0	0.1 0.1 0.1	— — —	V
			I _{OL} = 12mA	3.0	—	—	0.36	—	
			I _{OL} = 24mA	4.5	—	—	0.36	—	
			I _{OL} = 75mA*	5.5	—	—	—	—	
Input Leakage Current	I _{IN}	V _{IN} = V _{CC} or GND	5.5	—	—	± 0.1	—	± 1.0	μA
Quiescent Supply Current	I _{CC}	V _{IN} = V _{CC} or GND	5.5	—	—	8.0	—	80.0	

* : This spec indicates the capability of driving 50Ω transmission lines.

One output should be tested at a time for a 10ms maximum duration.

TIMING REQUIREMENTS (Input t_r = t_f = 3ns)

PARAMETER	SYMBOL	TEST CONDITION	Ta = 25°C		Ta = -40~85°C	UNIT
			V _{CC} (V)	LIMIT		
Minimum Pulse Width (CK)	t _W (L)		3.3 ± 0.3	8.0	8.0	ns
	t _W (H)		5.0 ± 0.5	5.0	5.0	
Minimum Pulse Width (CLR)	t _W (L)		3.3 ± 0.3	7.5	7.5	
			5.0 ± 0.5	5.0	5.0	
Minimum Set - up Time	t _s		3.3 ± 0.3	8.5	8.5	
			5.0 ± 0.5	4.5	4.5	
Minimum Hold Time	t _h		3.3 ± 0.3	0.0	0.0	
			5.0 ± 0.5	0.0	0.0	
Minimum Removal Time (CLR)	t _{rem}		3.3 ± 0.3	7.0	7.0	
			5.0 ± 0.5	3.5	3.5	

AC ELECTRICAL CHARACTERISTICS ($C_L = 50\text{pF}$, $R_L = 500\Omega$, Input $t_r = t_f = 3\text{ns}$)

PARAMETER	SYMBOL	TEST CONDITION		Ta = 25°C			Ta = − 40~85°C		UNIT
			V _{CC} (V)	MIN.	TYP.	MAX.	MIN.	MAX.	
Propagation Delay Time (CK—Q)	t _{pLH} t _{pHL}		3.3 ± 0.3 5.0 ± 0.5	— —	9.0 6.5	15.8 9.6	1.0 1.0	18.0 11.0	ns
Propagation Delay Time ($\overline{\text{CLR}}$ —Q)	t _{pHL}		3.3 ± 0.3 5.0 ± 0.5	— —	8.0 5.9	14.0 9.2	1.0 1.0	16.0 10.5	
Maximum Clock Frequency	f _{MAX}		3.3 ± 0.3 5.0 ± 0.5	55 90	110 150	— —	55 90	— —	MHz
Input Capacitance	C _{IN}			—	5	10	—	10	pF
Power Dissipation Capacitance	C _{PD} (1)			—	40	—	—	—	

Note (1) C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load.

Average operating current can be obtained by the equation :

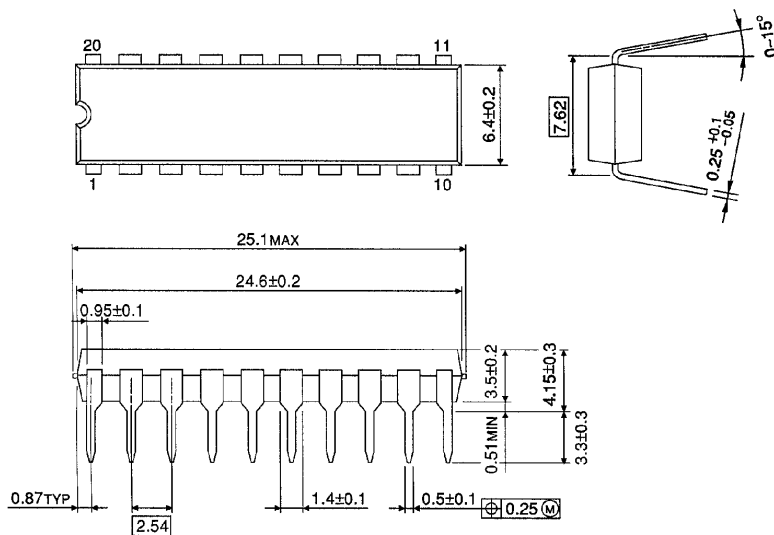
$$I_{CC}(\text{opr.}) = C_{PD} \cdot V_{CC} \cdot f_{IN} + I_{CC}/8 \text{ (per F/F)}$$

And the total C_{PD} when n pcs. of Flip Flop operate can be gained by the following equation :

$$C_{PD}(\text{total}) = 29 + 11 \cdot n$$

DIP 20PIN PACKAGE DIMENSIONS (DIP20-P-300-2.54A)

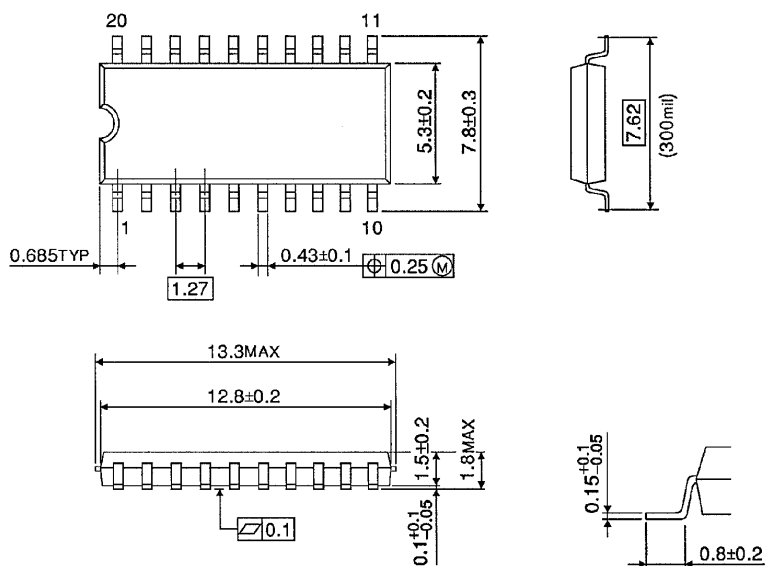
Unit in mm



Weight : 1.30g (Typ.)

SOP 20PIN (200mil BODY) PACKAGE DIMENSIONS (SOP20-P-300-1.27)

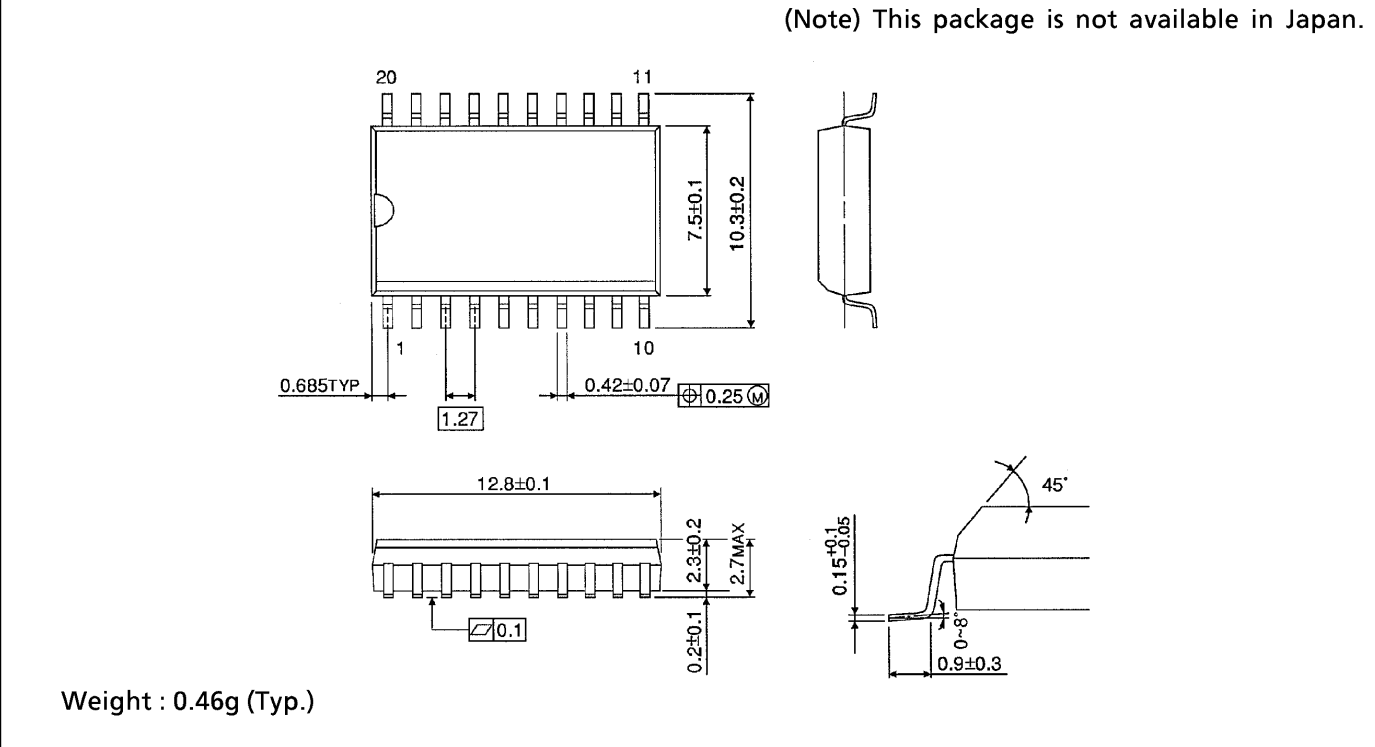
Unit in mm



Weight : 0.22g (Typ.)

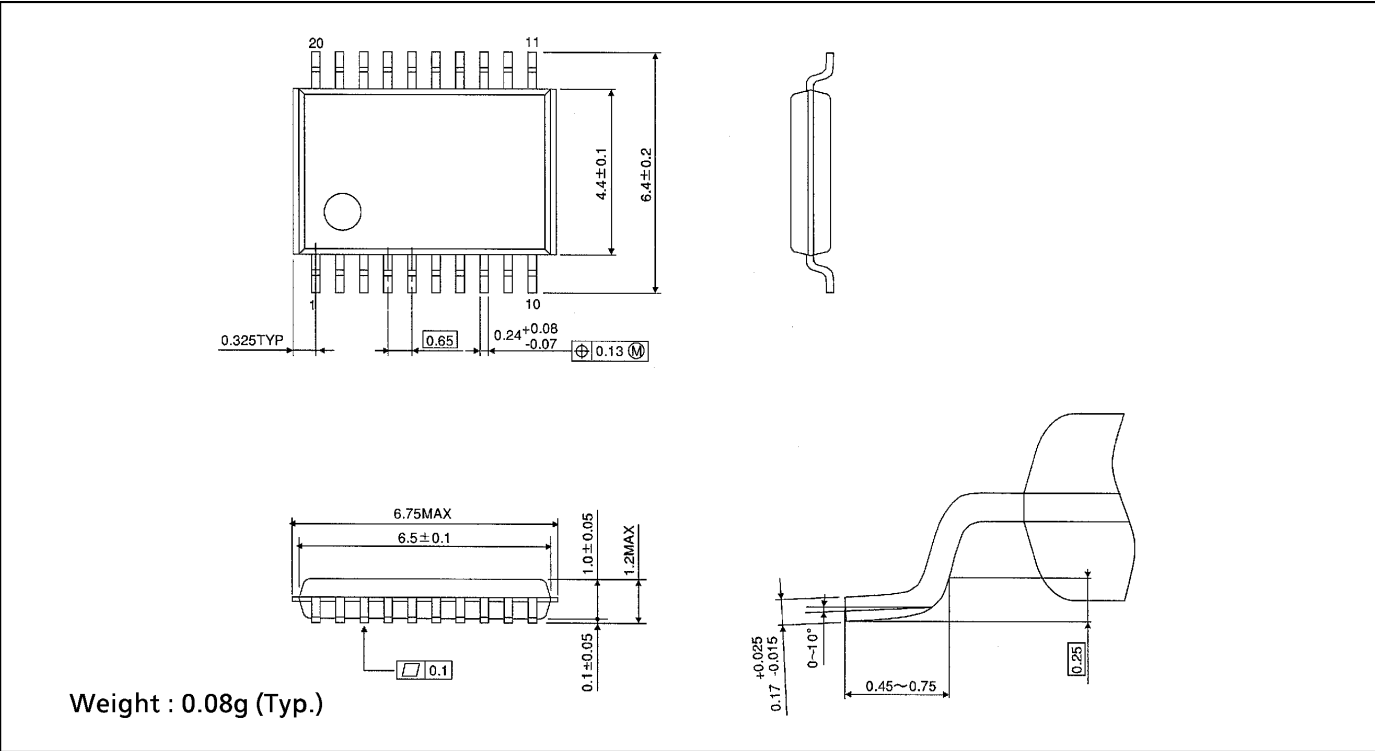
SOP 20PIN (300mil BODY) PACKAGE DIMENSIONS (SOL20-P-300-1.27)

Unit in mm



TSSOP 20PIN PACKAGE DIMENSIONS (TSSOP20-P-0044-0.65)

Unit in mm



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